

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(attachment adj layer) near10 (melting) near10 standoff	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:30
L2	18	(attachment adj layer) near10 (melting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:31
L3	6623	(spherical or sphere or core or solder or standoff or bead) near10 (melt or melting or melted) near10 (attachment or contact or pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:32
L4	956	(spherical or sphere or core or solder or standoff or bead) near10 (melt or melting or melted) near temperature near10 (attachment or contact or pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:32
L5	156	((spherical or sphere or core or solder or standoff or bead) near10 (melt or melting or melted) near temperature near10 (attachment or contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:32
L6	76	((spherical or sphere or core or solder or standoff or bead) near5 (melt or melting or melted) near temperature near5 (attachment or contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:33
L7	26	((spherical or sphere or core or solder or standoff or bead) near5 (melt or melting or melted) adj temperature near5 (attachment or contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:33
L8	56	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near5 (attachment or contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:35
L9	25	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near5 (lower or higher or greater or smaller) near5 (attachment or contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:35

L10	18	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 (attachment or contact or pad)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:36
L11	5	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 (attachment or contact or pad)). clm. and (pcb or board).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:37
L12	2	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 (attachment or contact or pad)). clm. with (pcb or board).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:37
L13	3	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 (attachment or contact or pad)). clm. same (pcb or board).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:37
L14	25	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 (attachment or contact or pad)) same (pcb or board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:39
L15	22	((spherical or sphere or core or solder or standoff or bead) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 ((attachment adj layer) or contact or pad)) same (pcb or board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:40
L16	23	((spherical or sphere or core or solder or standoff or bead or ball) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 ((attachment adj layer) or contact or pad)) same (pcb or board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:40

L17	6	(((spherical or sphere or core or solder or standoff or bead or ball) near5 ((melt or melting or melted) adj temperature) near (lower or higher or greater or smaller) near5 ((attachment adj layer) or contact or pad)) same (pcb or board)).ti, ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 11:40
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